



IN THE CLAIMS

Please amend the claims as follows:

Claims 1-24 (canceled)

Claim 25 (currently amended): A multilayer printed circuit board comprising:
a resin substrate [[board]] having, ~~on both sides thereof~~, a first surface and a second surface;

a first resin insulating layers each comprised of the same resin material layer formed over at least one of the first and second surfaces of the resin substrate, the first resin insulating layer comprising a thermosetting polyolefin resin;
a lower metal layer, having layers formed on the first resin insulating layer and being flat and level; and

a conductor circuit having the same pattern as said lower metal layer, on each of said first resin insulating layers circuit comprising a metal and formed on the lower metal layer,[[;
and]]

wherein ~~said resin insulating layers comprise thermosetting polyolefin resin;~~ said lower metal layers are composed of layer has a same pattern as said conductor circuit and comprises at least one metal selected from the group consisting of metals (~~exclusive of Cu~~) of the 4th through 7th periods in Group 4A through Group 1B of the long-form periodic table of the elements, Al, and Sn, excluding Cu; said conductor circuit comprises a metal; and each of said first resin insulating layers has a flat and level surface.

Claim 26 (currently amended): The multilayer printed circuit board according to Claim 25, wherein each of said lower metal layers is a layer containing comprises at least one metal selected from the group consisting of Al, Fe, W, Mo, Sn, Ni, Co, Cr, Ti and noble metals.

Claims 27-28 (canceled)

Claim 29 (currently amended): The multilayer printed circuit board according to
Claim 25, wherein ~~each of~~ said first resin insulating ~~[[layers]]~~ layer has a surface obtained by
plasma treatment or corona discharge treatment.

Claim 30 (currently amended): The multilayer printed circuit board according to
Claim 25, further comprising ~~wherein each of said conductor circuits has an upper metal~~
~~layer on its surface~~ said conductor circuit, wherein said upper metal layer ~~is composed of~~
~~comprises~~ at least one metal selected from the group consisting of metals ~~(exclusive of Cu)~~ of
the 4th through 7th periods in Group 4A through Group 1B of the long-form periodic table of
the elements, Al, and Sn, excluding Cu; and ~~said upper metal layer and~~ has a second resin
insulating layer or a solder resist layer thereon.

Claim 31 (currently amended): The multilayer printed circuit board according to
Claim 25, further comprising ~~a layer made of Cu interposed between the said lower metal~~
~~layer and said conductor circuit~~ ~~wherein each of said lower metal layers on the surface of said~~
~~first resin insulating layers has a Cu layer formed on its surface, and said conductor circuit is~~
~~constructed on said Cu layer.~~

Claim 32 (currently amended): The multilayer printed circuit board according to
Claim 25, wherein ~~the thickness of each of said lower metal layers is~~ layer has a thickness in
a range of 0.01 to 0.2 μ m.

Claims 33-63 (canceled)

Claim 64 (currently amended): The multilayer printed circuit board according to
Claim 25, wherein ~~each of~~ said lower metal ~~layers~~ layer is formed by plating, physical vapor
deposition or chemical vapor deposition.

Claim 65 (currently amended): The multilayer printed circuit board according to
Claim 25, wherein said thermosetting polyolefin resin has a dielectric constant value of not
more than 3 and a dielectric loss tangent value of not more than 0.05.

Claim 66 (canceled)

Claim 67 (currently amended): The multilayer printed circuit board according to
Claim 25, wherein comprising a successive series of units, each unit comprising the first resin
insulating layer, the lower metal layer on said first resin insulating layer and the conductor
circuit on said lower metal layer comprise a unit and said unit is formed in a successive series
on said resin substrate.

Claim 68 (currently amended): The multilayer printed circuit board according to
Claim 30, further comprising, on said second resin insulating layer, another lower metal layer
on said second resin insulating layer, and another conductor circuit made of a metal on said
another lower metal layer.

Claim 69 (currently amended): The multilayer printed circuit board according to
Claim 25, wherein said resin substrate board is comprises a copper-clad laminate, and has a
buildup structure on each side said first and second surfaces of said resin substrate.

Claim 70 (currently amended): The multilayer printed circuit board according to
Claim 30, wherein said upper metal layer is formed on the whole surface of covers said
conductor circuit entirely.

Claim 71 (new): The multilayer printed circuit board according to Claim 25, wherein
said first and second surfaces of said resin substrate have said first resin insulating layer, said
lower metal layer and said conductor circuit formed thereon.